

MECHANICAL CASE OUTLINE

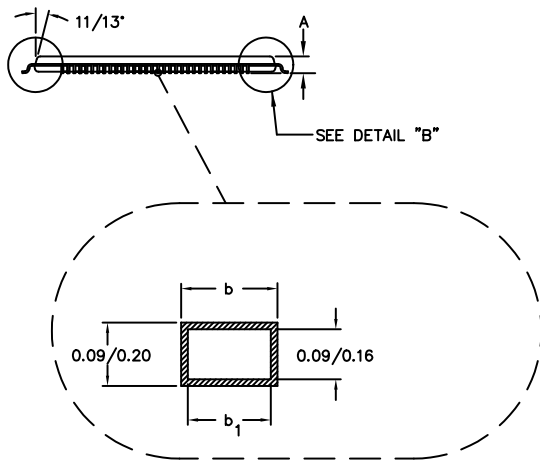
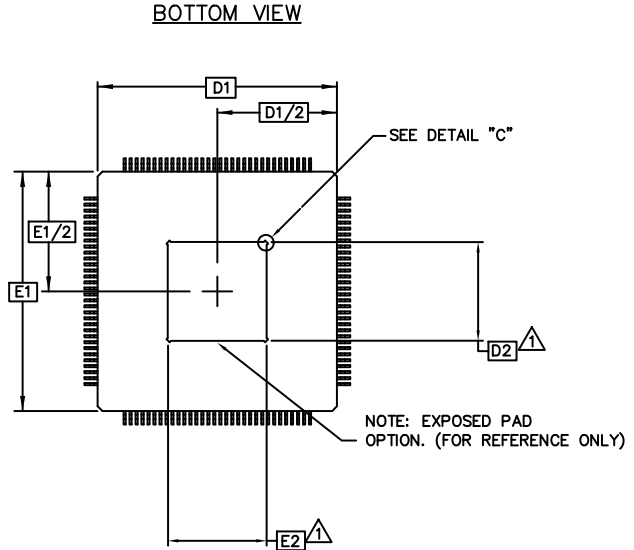
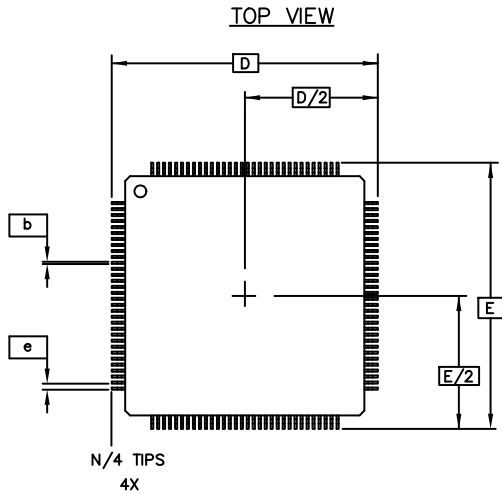
PACKAGE DIMENSIONS

ON Semiconductor®

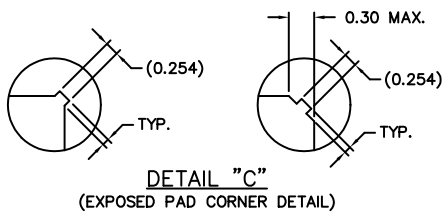
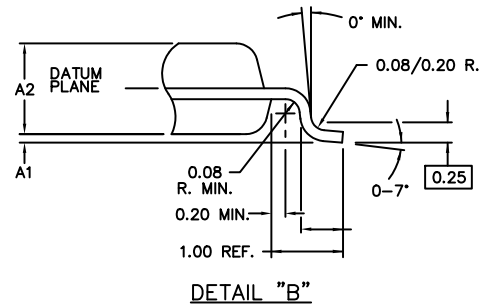


TQFP-64 EP, 10x10
CASE 136AC-01
ISSUE O

DATE 31 JUL 2008



⚠ DIMENSION D2 AND E2 REPRESENT THE SIZE OF THE EXPOSED PAD. THE ACTUAL DIMENSIONS ARE SPECIFIED ON THE BONDING DIAGRAM, AND IS DEPENDENT ON THE DIE SIZE.



SYMBOL	JEDEC VARIATION		
	ALL DIMENSIONS IN MILLIMETERS		
	ACD		
	MIN.	NOR.	MAX.
A	<i>~</i>	<i>~</i>	1.20
A1	0.05	<i>~</i>	0.15
A2	0.95	1.00	1.05
D	12.00 BSC.		
D1	10.00 BSC.		
E	12.00 BSC.		
E1	10.00 BSC.		
L	0.45	0.60	0.75
N	64		
e	0.50 BSC.		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23

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